

### REMARKS

Entry of the foregoing, reexamination and reconsideration of the subject matter identified in caption, as amended, pursuant to and consistent with 37 C.F.R. §1.112, and light of the remarks which follow are respectfully requested.

At the outset, the indication of allowable subject matter with respect to claim 18 is noted with appreciation.

As correctly noted in the Office Action Summary, claims 1-28 are pending in the application.

By the foregoing amendments, claim 25 has been revised in response to the objection, discussed below.

Turning now to the Official Action, the Examiner notes that International Publication No. WO 00/31771 could not be found, and requested submission on a form PTO-1449. Accordingly, a form PTO-1449 and a copy of the document are attached.

Claim 25 stands objected to for the inclusion of two periods. This objection has been obviated by the amendment to claim 25, by which the extra period has been deleted. Accordingly, withdrawal of this objection is respectfully requested.

Claim 1-5, 7-15 and 19-28 stand rejected under 35 U.S.C. §102(e) as being anticipated by Jayaraj et al (U.S. Patent No. 6,320,257). In addition, claims 6, 16 and 17 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Jayaraj et al. These rejections are respectfully traversed for at least the following reasons.

The present invention relates to a package for optical devices, and particularly to a module for operatively coupling one or more optical fibers with one or more optical devices. Claim 1, for example, sets forth an optical device package which comprises: a) a substrate comprising an upper surface; b) an optical fiber mounted to the substrate; c) a frame mounted to the upper surface of the substrate, the frame comprising conductive pathways extending between a top surface of the frame and a bottom surface of the frame; and d) contact means disposed on the top surface of the frame for flip mounting the optical device package to a platform. Independent claim 19 sets forth a method for making an optical device package and independent claim 22 sets forth a method for assembling an electronic circuit.

The claims cannot properly be rejected based on the teachings of Jayaraj et al. In this regard, it is well established, that in order to establish anticipation under §102, each element of the claim in issue must be found, either expressly described or under principles of inherency, in a single prior art reference. Kalman v. Kimberly-Clark Corp., 218 USPQ 789 (Fed. Cir. 1983). That is not the case here.

Jayaraj et al relates to chip packaging techniques, and in particular to multichip modules and techniques for the fabrication thereof. In setting forth the rejections, the Office relies on Figures 8B and 8C of Jayaraj et al.

Based on a complete understanding of applicants' invention and the applied Jayaraj et al document, it is respectfully submitted that the claims cannot properly be rejected based on the teachings of Jayaraj et al. In this regard, Jayaraj et al does not disclose or suggest each feature of the present invention. For example, Jayaraj et al does not disclose or fairly suggest: a frame mounted to the upper surface of a substrate, the frame comprising conductive pathways extending between a top surface of the frame and a bottom surface of the frame, as set forth in independent claim 1; mounting a frame to a substrate, the frame comprising a frame upper surface with at least one solder pad thereon, as set forth in independent claim 19; or a frame mounted to the upper surface of a substrate, the frame comprising an upper surface with a patterned array of solder balls thereon, as set forth in independent claim 22.

The Official Action points to LCP (liquid crystal polymer) substrate 122 in an effort to establish the presently claimed "frame" recitations. However, LCP substrate 122 cannot properly be deemed a frame. Jayaraj et al discloses "picture frame 20" in connection with Figure 8B and C (col. 8, lines 48-49). Picture frame 20 does not, however, include any of the aforementioned features relating to conductive pathways, solder pads, or solder balls.

For at least the foregoing reasons, independent claims 1, 19 and 22, and their respective dependent claims are allowable over the applied Jayaraj et al document.

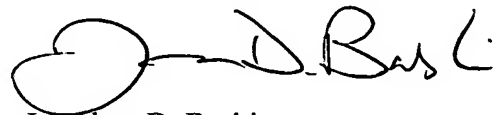
Moreover, even assuming (incorrectly) that Jayaraj et al's LCP substrate 122 is a frame as set forth in the independent claims, various dependent claims further distinguish over that document. For example, Jayaraj et al does not disclose or fairly suggest that conductive pathways comprise at least one conductive via which extends through the

frame, as set forth in claim 2. Figure 2B of Jayaraj et al illustrates the electrical layout of an LCP substrate, and no conductive via appears to extend through the frame. Nor does that document appear to disclose or suggest at least one conductive path which extends along a side surface of the frame, as set forth in claim 3. Claims 11 sets forth that the frame comprises an interior ledge. It is not at all apparent what portion of Jayaraj et al is relied on for such feature. Claims 12, 13 and 20 relate to a lid mounted to the frame or frame ledge. In rejecting these claims, the Official Action relies on Figure 8B. This is an entirely different embodiment from Figure 8C, which is relied on in rejecting claim 1. There is no disclosure or suggestion in Jayaraj et al to use a lid in Figure 8C in addition to the LCP substrate, since the device is hermetically sealed. Claims 16 and 17 recite that the frame comprises a band-like shape circumscribing an open area and a U-shaped configuration, respectively. The LCP substrate of Jayaraj et al is in no way suggestive of these claimed structures. It should be clear that other dependent claims, while not mentioned specifically, also further distinguish over the applied document.

From the foregoing, further and favorable action in the form of a Notice of Allowance is believed to be next in order, and such action is earnestly solicited.

If there are any questions concerning this paper or the application in general, the Examiner is invited to telephone the undersigned in order to expedite prosecution.

Respectfully submitted,



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